



US011913989B2

(12) **United States Patent**
Rascon et al.

(10) **Patent No.:** **US 11,913,989 B2**
(45) **Date of Patent:** **Feb. 27, 2024**

(54) **BURN-IN BOARD INCLUDING STRIP SOCKET WITH INTEGRATED HEATING FOR HIGH VOLUME BURN-IN OF SEMICONDUCTOR DEVICES**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 479 days.

(21) Appl. No.: **17/174,392**

(22) Filed: **Feb. 12, 2021**

(65) **Prior Publication Data**

US 2021/0255237 A1 Aug. 19, 2021

Related U.S. Application Data

(60) Provisional application No. 62/977,779, filed on Feb. 18, 2020.

(51) **Int. Cl.**
G01R 31/28 (2006.01)
H01R 33/88 (2006.01)
(Continued)

(52) **U.S. Cl.**
CPC **G01R 31/2863** (2013.01); **G01R 31/2875** (2013.01); **H01R 12/88** (2013.01);
(Continued)

(58) **Field of Classification Search**
CPC G01R 31/2856; G01R 31/2875; G01R 31/2877

See application file for complete search history.

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(57) **ABSTRACT**

A burn-in board for burn-in testing of semiconductor devices includes a strip socket mounted to a PCB. The strip socket includes a socket base configured to receive a device strip including an array of semiconductor devices, and a socket lid including at least one heating block. The socket lid is movable moved between (a) an open position allowing the device strip to be mounted on the socket base and (b) a closed position in which the socket lid including the heating block(s) is closed down on the mounted device strip. The strip socket includes conductive contacts configured to contact individual semiconductor devices on the device strip to allow selective monitoring of individual semiconductor devices during a burn-in test process. The burn-in board may also include heating control circuitry to control the heating block(s) during the burn-in test process.

21 Claims, 22 Drawing Sheets

